

# Physical Interfaces & Carriers

## Japan TC Chapter

### Liaison Report

**July 3, 2017**

Ver. 0.1

# Outline

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- Current Structure of PI&C Japan TC Chapter
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# Leadership

- Committee Co-chairs
  - Tsuyoshi Nagashima (Miraial)
  - Kenji Yamagata (DAIFUKU)
  - Noriyoshi Toyoda (Hirata Corporation)
- Technical Architect
  - Shoji Komatsu (Acteon NEXT)

# Current Structure of Japan TC Chapter

The TF is under the Japan TC Chapters of Silicon Wafers, PI&C, I&C, Traceability and Assembly & Packaging. The TF's discharge will be completed when agreed by all those TC Chapters. All the committees other than Traceability agreed the discharge.

## Physical Interfaces & Carriers

### Japan TC Chapter

Tsuyoshi Nagashima (Miraial)  
Kenji Yamagata (Daifuku)  
Noriyoshi Toyoda (Hirata Corporation)

#### Technical Architect

Shoji Komatsu / Acteon NEXT

### Fiducial Mark Interoperability TF

I&C Committee: M. Matsuda (Hitachi Kokusai Electric)  
PI&C Committee: S. Mashiro (Tokyo Electron)  
Silicon Wafer Committee: T. Nakai (SUMCO)  
Packaging Committee: S. Masuchi (DISCO)  
Traceability Committee: H. Tsunobuchi (KEYENCE)

#### JA Shipping Box TF

Tsuyoshi Nagashima (Miraial)  
Shoji Komatsu (Acteon NEXT)

#### International 450mm Shipping Box TF

Tom Quinn (Intel)  
Shoji Komatsu (Acteon NEXT)

Under Silicon Wafer Japan TC Chapter

### Global PIC Maintenance TF

Larry Hartsough (U.A. Associates)  
Shoji Komatsu (Acteon NEXT)

### International 450 mm PI&C TF

Melvin Jung (Intel)

TF under PIC Japan TC Chapter was discharged, accordingly Shoji Komatsu (Acteon NEXT) stepped down from the co-leader.

### International Reticle SMIF Pod and Lord Port Interoperability TF

Jan Rothe (GLOBALFOUNDRIES)

TF under PIC Japan TC Chapter was discharged

International Activities

# Meeting Information

- Last meeting
  - Japan Spring 2017 Meetings
    - Wednesday, April 19, 2017 13:30-17:00
    - @SEMI Japan office, Tokyo
- Next meeting
  - Japan Summer 2017 Meetings
    - Wednesday, July 26, 2017 14:00-17:00
    - @SEMI Japan office, Tokyo

# Document Review Summary at Japan Spring 2017 Meetings [1/2]

Cycle 1 –2017		
Doc #	Description	Japan Chapter Action
6130	Reapproval of SEMI E84-1109, “SPECIFICATION FOR ENHANCED CARRIER HANDOFF PARALLEL I/O INTERFACE”	Passed as balloted

Passed A&R in May 2017 and waiting for the proof.

# Document Review Summary at Japan Spring 2017 Meetings [2/2]

- 5974: New Auxiliary Information: “450mm PIC INTEROPERABILITY”
  - The Japan TC Chapter authorized the publication of this document at the TC Chapter meeting held on December 14, 2016 in conjunction with SEMICON Japan 2016 and the publication of this document was subsequently approved by the GCS on January 17, 2017. However, it was found that the safety check and the IP check for the document were not completed along with the authorization for publication at that TC Chapter meeting. Therefore, these checks were completed at the next TC Chapter meeting held on April 19, 2017
  - Passed A&R in May 2017
  - Published as AUX033-0617 in June 2017

# Ballots to be reviewed at Japan Summer 2017 Meetings

- None



# Activities Approved by the GCS between meetings of TC Chapter meeting

- None

# Approved SNARF at Japan Spring 2017 Meetings

- None

# SNARF(s) Granted a One-Year Extension / SNARF(s) Abolished

- None

# Standard to received Inactive Status

- None

# Task Force Updates [1/3]

- Fiducial Mark Interoperability TF
  - Last TF meeting was held on November 18, 2015
  - Disbandment of this TF
    - TF leaders decided to propose disbanding this TF to each technical committee
    - If this proposal is agreed by all Japan TC Chapters of Assembly & Packaging, I&C, PIC, Silicon Wafers and Traceability, then the TF will be discharged.
      - The Silicon Wafers agreed on March 9, Assembly & Packaging agreed on March 13, PI&C agreed on April 19 and the I&C agreed on April 21.
      - To be proposed at the next Japan TC Chapter meeting of Traceability.
  - Backend alignment issues with introducing fiducial mark wafer is left.
    - Would be discussed in Assembly & Packaging Japan TC Chapter after its disbandment.

# Task Force Updates [2/3]

- Global PIC Standards Maintenance Task Force (JA Side)
  - #6130, Reapproval of SEMI E84-1109, “SPECIFICATION FOR ENHANCED CARRIER HANDOFF PARALLEL I/O INTERFACE”
    - SNARF was approved at the PIC Japan TC Chapter meeting on December 14, 2016
    - Ballot was submitted for Cycle 1-2017
      - Rejects and comments to be reviewed at the TF meeting during NA Standards Spring 2017 Meetings
      - Ballot results were reviewed and passed as balloted at the PIC Japan TC Chapter meeting on April 19, 2017.
      - Passed A&R in May 2017 and waiting for the proof.
  - The information of AUX033-0617 (#5974) should be added to “Referenced Standards and Documents” section of SEMI E154, SEMI E158 and SEMI E159 respectively. Since International 450 mm Physical Interfaces & Carriers TF is discharged, this proposal will be made by the Global PIC Standards Maintenance Task Force.

# Task Force Updates [3/3]

- International 450 mm Physical Interfaces & Carriers Task Force (JA Side)
  - #5974: New Auxiliary Information: “450mm PIC INTEROPERABILITY”
    - The Japan TC Chapter authorized the publication of this document at the TC Chapter meeting held on December 14, 2016 in conjunction with SEMICON Japan 2016 and the publication of this document was subsequently approved by the GCS on January 17, 2017. The safety check and the IP check for the document were completed at the next TC Chapter meeting held on April 19, 2017
    - Published as AUX033-0617 in June 2017
  - Approved the discharge of International 450 mm PIC TF under PI&C Japan TC Chapter at the TC Chapter meeting held on April 19, 2017.

## Other topic

- Proposal of New Standards, Specification for Lamella Carriers Used in Transmission Electron Microscopes
  - According to the decision at the EU TC Chapter meeting in October during SEMICON Europa 2016, the meeting to introduce proposal was held on December 13 at SEMI Japan Office in conjunction with SEMICON Japan 2016
    - Back ground of this standardization
    - Presentation on “Enabling HVM TEM metrology support - standards for TEM lamella carriers”
    - Proposed drafts of SNARF and TFOF
  - The Japan TC Chapter agreed to support for conducting a survey regarding standardization of TEM and potential further standardization of TEM grid carrier.
    - SEMI HQ conducted this survey in June 2017.
      - The results to be reviewed and discussed at the NA TC Chapter meeting at SEMICON West 2017.



# Thank You!

For more information or participate in any Japan  
PI&C activities,  
please contact Chie Yanagisawa at SEMI Japan  
([cyanagisawa@semi.org](mailto:cyanagisawa@semi.org))